



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Kinsman et al.

**Serial No.:** 09/917,127

**Filed:** July 27, 2001

**For:** METHOD FOR FABRICATING A  
CHIP SCALE PACKAGE USING WAFER  
LEVEL PROCESSING AND DEVICES  
RESULTING THEREFROM

**Confirmation No.:** 3326

**Examiner:** M. Trinh

**Group Art Unit:** 2822

**Attorney Docket No.:** 2269-3572.1US  
(97-1243.01/US)

**Notice of Allowance Mailed:**

January 26, 2004

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Person making Deposit: Christopher Haughton

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Remarks** begin on page 3 of this paper.